Claims

1. Method for producing chip stacks (31) with the following method sequence:

- applying a base layer (20) to one carrier side (15) of a carrier (10) which on its carrier side (15) is provided with an adhesively acting adhesion zone (14) and a less adhesively acting support zone (11), the base layer (20) being applied by spin coating, spray coating or lamination at least largely over the entire surface of the support zone (11),
- building up the chip stacks (31) on the base layer (20), wherein the base layer (20) will at least partially get part of the chip stacks (31),
- detaching the carrier (10) from the base layer (20).

2. Method as claimed in Claim 1, wherein on the carrier side (15) in the adhesion zone (14) there is a selectively soluble fill material (13), especially on an offset (12) which has been set back relative to the carrier side (15), preferably superficially flush toward the carrier side (15).

3. Method as claimed in Claim 1, wherein the base layer (20) is applied to the support zone (11) over the entire surface and at least partially to the adhesion zone (14).

4. Method as claimed in Claim 1, wherein the chip stacks (31) are separated before detachment of the carrier (10), especially by cutting, so that the chip stacks (31) are only still connected to the carrier (10).

5. Method as claimed in Claim 1, wherein the material which forms the base layer (20) is flexible.

6. Method as claimed in Claim 1, wherein especially before building up the chip stacks (31) fan-out bonding structures (21) are made in the base layer (20).

7. Method as claimed in Claim 6, wherein before building up the chip stacks (31) on one chip side (24) facing away from the carrier side (15) contact pads (22) for electrical bonding of the chip stacks (31) with the fan-out bonding structures (21) are applied.

8. Method as claimed in Claim 6, wherein before or during the build-up of the chip stacks (31), especially at the same time with the introduction of the fan-out bonding structures (21) as claimed in Claim 6, there are alignment marks (25) for positioning/ placement of the contact pads (22) and/or the chip stacks (31) on the base layer (20), especially flush with one edge (32) of the chip stacks (31), in/on the base layer (20).

9. Method as claimed in Claim 1, wherein the chip stacks (31) are cemented directly on the base layer (20) by bonding.

10. Method as claimed in one of the preceding claims, wherein after building up the chip stacks (31) and before detaching the carrier (10) the chip stacks are potted with a layer material (40) which corresponds especially to the material of the base layer (20).

11. Method as claimed in Claim 2, wherein the carrier (10) is detached from one side edge of the carrier (10), especially by reducing the adhesion force of the adhesion layer (14), preferably by selective dissolution of the fill material (13).

12. Method as claimed in one of the preceding claims, wherein base parts (26) of the base layer (20) form one part of each chip stack (31).

13. Method for producing chip stacks (31) with the following method sequence:

- applying a base layer (20) to one carrier side (15) of a carrier (10) which on its carrier side (15) is provided with an adhesively acting adhesion zone (14, the base layer (20) being applied by spin coating, spray coating or lamination over the entire surface to the adhesion zone (14), and one contact surface of the adhesion zone (14) with the base layer (20) before application of the base layer (20) being subjected to surface modification to reduce the free surface energy,
- building up the chip stacks (31) on the base layer (20), wherein the base layer (20) will at least partially get part of the chip stacks (31),
- detaching the carrier (10) from the base layer (20).

14. Carrier (10) which is provided on one carrier side (15) with an adhesively acting adhesion zone (14) and a less adhesively acting support zone (11), a base layer (20) being applicable by spin coating, spray coating or lamination at least largely over the entire surface of the support zone (11), and on the carrier side (15), in the adhesion zone (14), there being a selectively soluble fill material (13) on an offset (12) which is set back relative to the carrier side (15), wherein chip stacks (31) are built on the base layer (20), and wherein the base layer (20) will at least partially get part of the chip stacks (31).